

1. An o-ring monitoring device for a vacuum system comprising:
a piezoelectric element with a pair of ends for externally connecting to a
signal processor;
said piezoelectric element disposed and placed to be fully insulated within
5 a mold cavity, said mold cavity having a predetermined diameter and
cross-section shape;
said mold cavity filled with an elastic material encapsulating said
piezoelectric element therein.

10 2. The monitoring device of claim 1 wherein a voltage “ q ” is generated as
feedback to said signal processor, said voltage “ q ” is proportional to the amount
of applied force “ F_q ”, is given as;

$$q = [d]\chi_i F_q$$

where $[d]\chi_i$ is the piezoelectric constant.

15 3. The monitoring device of claim 1 wherein said piezoelectric element is
selected from the group consisting of quartz, rochelle salt, barium titanate, lead
zirconate, and lead titanate.

4. The monitoring device of claim 1 wherein said elastic material is
selected from the group consisting of all rubber compounds used for sealing
20 applications.

5. The sealing device of claim 1 wherein said conducting charge collectors

attached on opposite sides of said oblong cross-section are used to provide a reading of seal compression.

25 6. The sealing device of claim 1 wherein circumferentially encapsulating said piezoelectric element within an o-ring provides real-time monitoring of o-ring performance during ultra-high vacuum operations.

 7. The sealing device of claim 6 wherein said real-time monitoring of
30 o-ring performance eliminates lengthy maintenance problem-solving studies, most importantly, early detection precludes product waste, shortens debug time, and increases machine utilization.

 8. The sealing device of claim 6 wherein said real-time monitoring of
35 an o-ring performance eliminates back-tracking to find product defects caused by undetected o-ring failure.

 9. A vacuum system comprising an o-ring sealing device.
 said o-ring sealing device having a piezoelectric element molded therein;
40 said piezoelectric element having a pair of lead wires that egress from an outer and side periphery of said o-ring;
 said o-ring sealing device placed in an o-ring groove and compressed between two surfaces;
 said pair of lead wires connected to a signal processor.

- 45 10. The o-ring sealing device according to claim 9 wherein said
compression between two flanged surfaces generate a feedback voltage value “ q ”
to said signal processor, said feedback voltage is proportional to the amount of
compressive force “ F_q ”, is given as;

$$q = [I]\chi_i F_q$$

- 50 where $[I]\chi_i$ is the piezoelectric constant.

11. The o-ring sealing device according to claim 10 wherein “ q ” stabilizes
after a desired vacuum level is reached, any variance thereafter signifies a change
in compressive force “ F_q ”, indicating a warning of a potential leak or of a
defective o-ring.

- 55 12. The o-ring sealing device according to claim 9 wherein a plurality of
o-ring sealing devices used in a vacuum system simplifies maintenance debug by
immediately indicating the position of a defective o-ring by providing a feedback
signal indicating a specific o-ring failure during the vacuum process.

- 60 13. The o-ring sealing device according to claim 12 wherein said plurality
of o-ring sealing devices used in a vacuum system eliminates the otherwise
time consuming search for a defective seal which causes a high number of defects
before it is identified as being defective.

14. A method for monitoring compression stability of an o-ring seal during
vacuum operations, comprising the steps of:

- 65 providing an o-ring seal with a piezoelectric element encapsulated

therein;

said piezoelectric element with a pair of ends for externally connecting to

a signal processor;

said piezoelectric element placed within a mold cavity of a predetermined

70 diameter and cross-section shape;

said mold cavity filled with an elastic material for molding an o-ring

having a fully encapsulated and insulated piezoelectric element;

curing said molded o-ring, and

placing said molded o-ring with an encapsulated piezoelectric element in

75 an o-ring groove for sealing a vacuum chamber;

connecting said pair of ends of said conducting charge collectors to a

signal processor for monitoring compression stability of said o-ring.

15. The method of claim 14 wherein a voltage “ q ” is generated as

80 feedback to said signal processor, said voltage “ q ” is proportional to the amount

of applied force “ F_q ”, is given as;

$$q = [I]\chi_i F_q$$

where $[I]\chi_i$ is the piezoelectric constant.

85 16. The method of claim 14 wherein said piezoelectric element is

selected from the group consisting of quartz, rochelle salt, barium titanate, lead

zirconate, and lead titanate.

17. The method of claim 14 wherein said elastic material is selected
90 from the group consisting of all rubber compounds used for sealing applications.

18. The method of claim 14 wherein said conducting charge collectors
attached on opposite sides of said oblong cross-sectional shape are used to provide
an output value of seal compression.

95 19. The method of claim 14 wherein said piezoelectric element that is
encapsulated within an o-ring provides real-time monitoring of an o-ring's
performance during vacuum operations.

100 20. The method of claim 19 wherein said real-time monitoring to
determine o-ring performance eliminates lengthy problem-solving studies while
early detection precludes product waste, shortens debug time and increases
machine utilization.

105 21. The method of claim 19 wherein said real-time monitoring for
o-ring performance eliminates back-tracking to find product defects caused by
undetected o-ring failure.